

# Intel® 82551ER Fast Ethernet Controller

Compare

+

Specifications	^
Essentials	
Networking Specifications	
Package Specifications	
Advanced Technologies	
Ordering / sSpecs / Steppings	▼

Specifications	
Essentials	
Status	End of Life
Launch Date	Q1'02
Lithography	350 nm
TDP	0.61 W
Recommended Customer Price	N/A
Datasheet	<a href="#">Link</a>
Operating Temperature Range	0°C to 85°C
Networking Specifications	
# of Ports	Single
System Interface Type	PCI
NC Sideband Interface	No
Jumbo Frames Supported	No
Package Specifications	
Package Size	15x15mm
Low Halogen Options Available	See MDDS
Advanced Technologies	
Fiber Channel over Ethernet	No
MACsec IEEE 802.1 AE	No
IEEE 1588	No
Supported Under vPro	No

Related Products
<a href="#">Intel® Fast Ethernet Network Connections</a>
<a href="#">Intel® 82551 Fast Ethernet Controller</a>
<a href="#">Products formerly Lavon</a>
Quick Links
<a href="#">Export Full Specifications &gt;</a>
<a href="#">Support Overview &gt;</a>
<a href="#">Search Distributors &gt;</a>
PCN/MDDS Information
<b>SL66X</b>
844686: <a href="#">PCN</a>   <a href="#">MDDS</a>
<b>SL7G4</b>
860614: <a href="#">PCN</a>   <a href="#">MDDS</a>
844687: <a href="#">PCN</a>   <a href="#">MDDS</a>
860613: <a href="#">PCN</a>   <a href="#">MDDS</a>

All information provided is subject to change at any time, without notice. Intel may make changes to manufacturing life cycle, specifications, and product descriptions at any time, without notice. The information herein is provided "as-is" and Intel does not make any representations or warranties whatsoever regarding accuracy of the information, nor on the product features, availability, functionality, or compatibility of the products listed. Please contact system vendor for more information on specific products or systems.

"Intel classifications" consist of Export Control Classification Numbers (ECCN) and Harmonized Tariff Schedule (HTS) numbers. Any use made of Intel classifications are without recourse to Intel and shall not be construed as a representation or warranty regarding the proper ECCN or HTS. Your company may be the exporter of record, and as such, your company is responsible for determining the correct classification of any item at the time of export.

Refer to Datasheet for formal definitions of product properties and features.


"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

"Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers.

The Recommended Customer –unit purchase quantities, and are subject to change without notice. Taxes and shipping, etc. not included. Prices may vary for other package types and shipment quantities, and special promotional arrangements may apply. If sold in bulk, price represents individual unit. Listing of these RCP does not constitute a formal pricing offer from Intel. Please work with your appropriate Intel representative to obtain a formal price quotation.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

 [Send us your feedback!](#)

